

WLCSP6 1.11x0.98x0.35 CASE 567ZZ

ASE 567ZZ ISSUE O

NOTE 6

DETAIL A

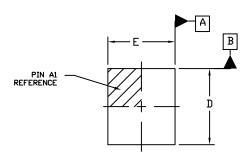
АЗ

A2

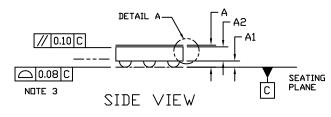
BACKSIDE

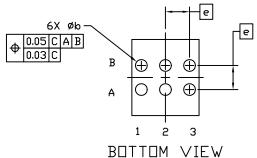
COATING

DATE 09 NOV 2021



TOP VIEW





GENERIC
MARKING DIAGRAM*



XXXX = Specific Device Code

A = Assembly Location

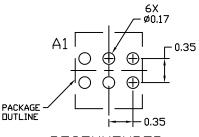
Y = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. DIMENSION 6 IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
- 6. BACKSIDE COATING IS OPTIONAL.

	MILLIMETERS		
DIM	MIN.	MAX.	
Α		0.35	
A1	0.080	0.100	
A2	0.205 REF		
A3	0.025 REF		
b	0.15	0.19	
D	1.091	1.121	
Ε	0.961	0.991	
е	0.35 BSC		



RECOMMENDED MOUNTING FOOTPRINT

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